Unit: mm

TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type(π -MOS IV)

TK09H90A

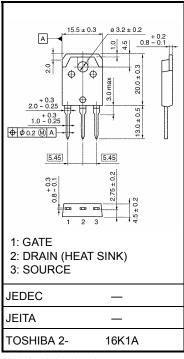
Switching Regulator Applications

• Low drain-source ON resistance : $RDS (ON) = 1.0\Omega (typ.)$ • High forward transfer admittance : $|Y_{fs}| = 6S (typ.)$

• Low leakage current : $IDSS = 100 \mu A (max) (VDS = 720V)$ • Enhancement mode : $V_{th} = 2.0 \sim 4.0 V (VDS = 10 V, ID = 1 mA)$

Absolute Maximum Ratings (Ta = 25°C)

Character	istic Sy	mbol	Rating	Unit	
Drain-source voltage		V _{DSS} 90	0	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	900	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	9	Α	
	Pulse (Note 1)	I _{DP} 27		А	
Drain power dissipation (Tc = 25°C)		P_{D}	150	W	
Single-pulse avalanche energy (Note 2)		E _{AS} 77	8	mJ	
Avalanche current		I _{AR}	9	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	−55~150 °	С	



Weight: 3.8 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

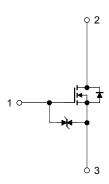
Characteristic Sy	mbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)} 0	.833	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)} 50		°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 17.6 mH, R_G = 25 Ω , I_{AR} = 9 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



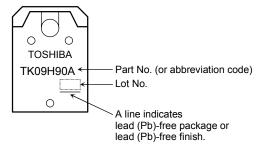
Electrical Characteristics (Ta = 25°C)

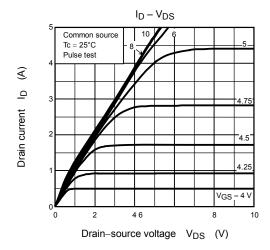
Chara	cteristic Sy	mbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V	_	_	±10	μΑ	
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V	
Drain cutoff curr	ent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μA	
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	900	_	_	V	
Gate threshold v	roltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V	
Drain-source O	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 4.0 A	_	1.0	1.3	Ω	
Forward transfer	admittance	Y _{fs} V	_{DS} = 10 V, I _D = 4.0 A	3.5	6.0	_	S	
Input capacitano	е	C _{iss} —			2200	_		
Reverse transfer capacitance		C _{rss} —	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		45	_	pF	
Output capacitance		C _{oss}			0 —	-		
Switching time	Rise time	t _r —	$V_{GS} = 10V \qquad I_{D=4A} \circ V_{out}$ $V_{GS} = 100 \Omega$ $V_{DD=400V}$ $V_{DD=400V}$ $V_{DD=400V}$		25	_	- ns	
	Turn on time	t _{on} —			65	_		
	Fall time	t _f —			20	_		
	Turn off time	t _{off}		_	120	_		
Total gate charg plus gate-drain)		Q _g —			60			
Gate-source charge		Q _{gs} —	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 9 \text{ A}$		34	_	nC	
Gate-drain ("Miller") charge		Q_{gd}				_		

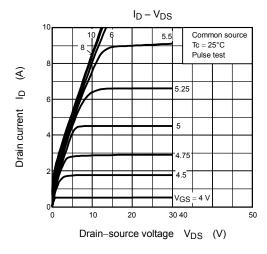
Source-Drain Ratings and Characteristics (Ta = 25°C)

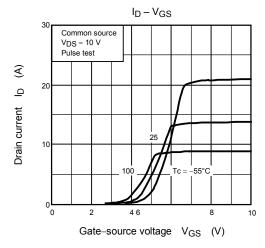
Characteristic Sy	mbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (N ote 1)	I _{DR} —		_	_	9	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	27	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 9 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 9 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs	_	1450		ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs	— 17		_	μC

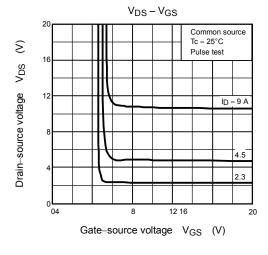
Marking

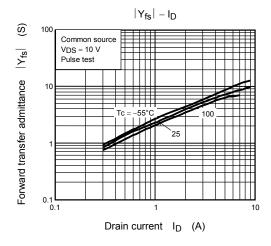


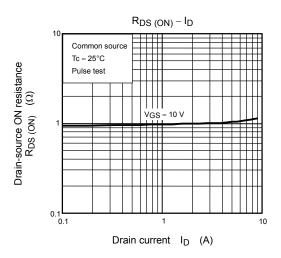


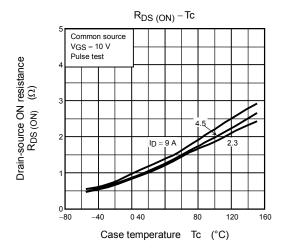


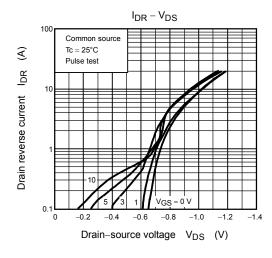


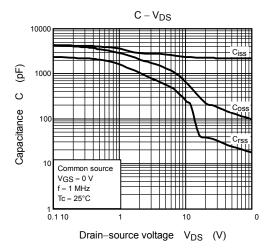


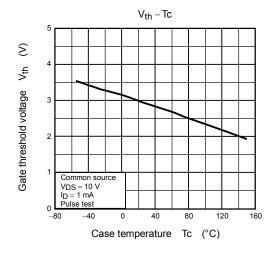


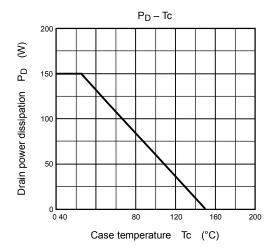


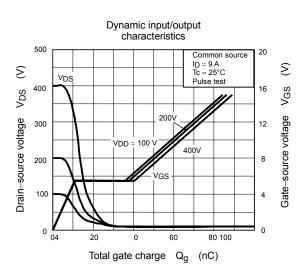




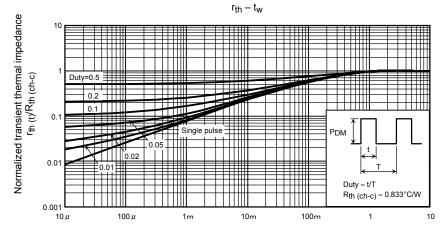




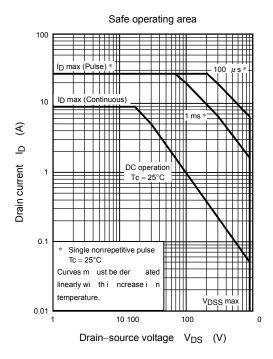


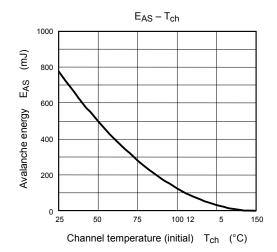


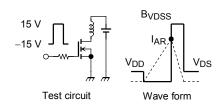
4



Pulse width t w (s)







$$R_G = 25 \Omega$$

 $V_{DD} = 90 \text{ V}, L = 17.6 \text{ mH}$

$$\mathsf{EAS} = \frac{1}{2} \cdot L \cdot l^2 \cdot \left(\frac{\mathsf{BVDSS}}{\mathsf{BVDSS} - \mathsf{VDD}} \right)$$

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